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9. The connector assembly according to claim 1, wherein a signal path between the signal pin of the connector and the device in the chip carrier is less than 75 mils.

10. The connector assembly according to claim 1, wherein a signal path between the signal pin of the connector and the device in the chip carrier is less than 40 mils.

11. The connector assembly according to claim 1, wherein the cavity receives a substantial portion of the chip carrier.

12. The connector assembly according to claim 1, wherein the chip carrier is substantially flush with a surface of the flange.

13. The connector assembly according to claim 1, wherein the cavity is located at a center portion of the flange.

14. The connector assembly according to claim 13, wherein the cavity is symmetrically centered in the flange.

15. The connector assembly according to claim 1, wherein the chip carrier includes one of a semiconductor device and an optical driver.

16. The connector assembly according to claim 1, wherein the plurality of pins have a coplanar pin configuration and include a signal pin and two ground pins, the signal pin being connected to a device in the chip carrier.

17. The connector assembly according to claim 16, wherein the chip carrier includes a conductive line connecting the signal pin of the connector to the device in the chip carrier.

18. The connector assembly according to claim 17, wherein the conductive line is coplanar with the signal pin.

19. The connector assembly according to claim 18, wherein the conductive line is bent prior to contacting the device.

20. The connector assembly according to claim 17, wherein the conductive line is less than 100 mils.

21. The connector assembly according to claim 17, wherein the conductive line is less than 50 mils.

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